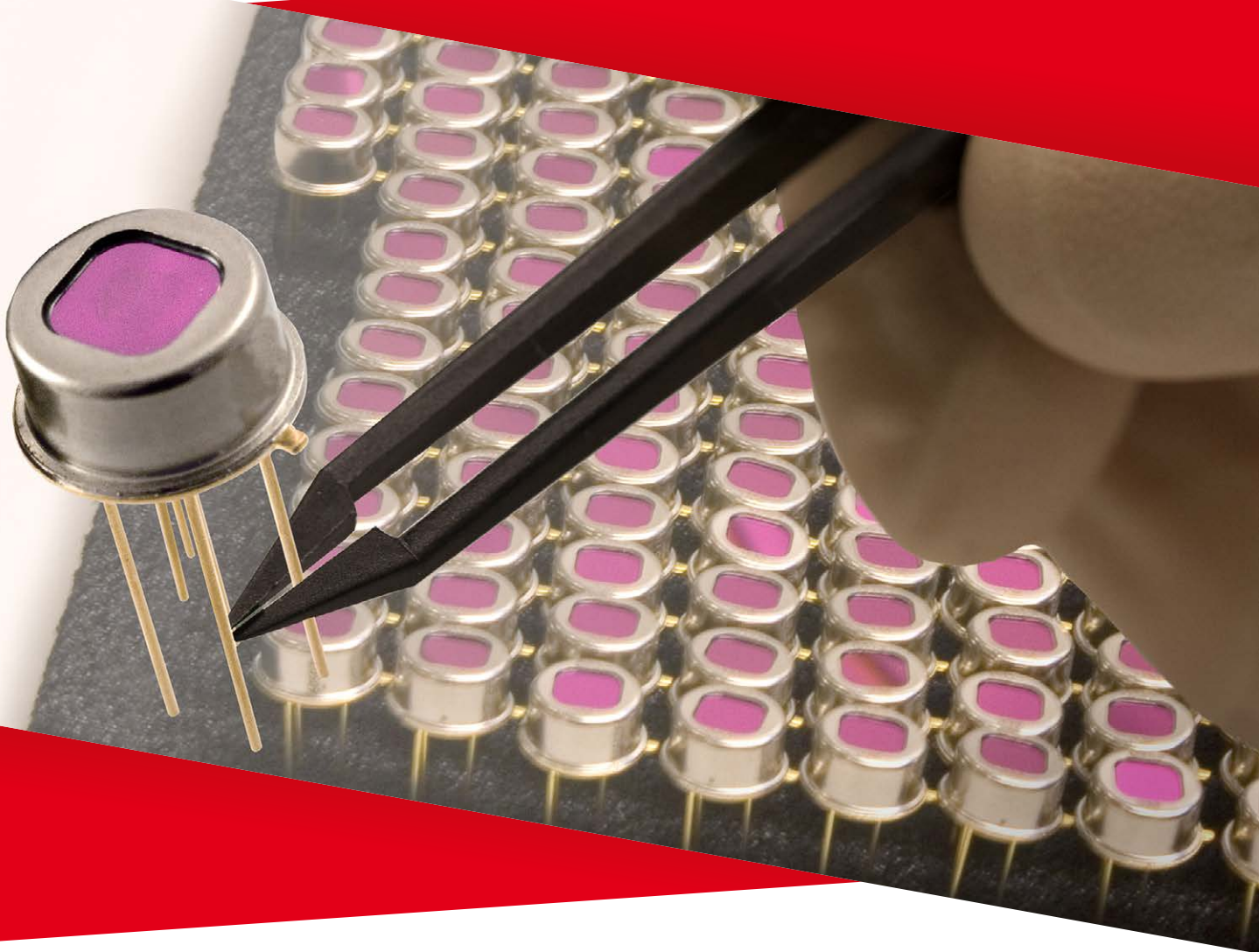


Handling Recommendations

Safe transport, storage and processing of sensitive infrared detectors

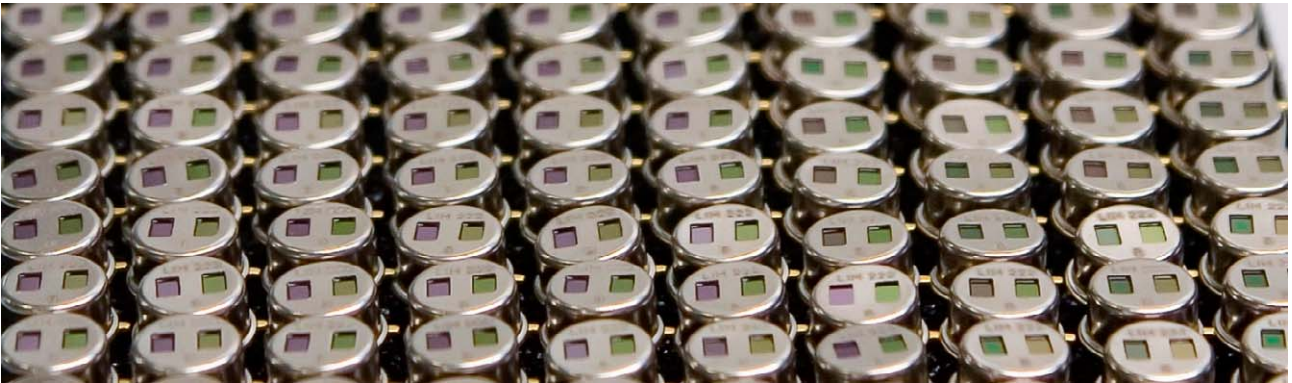


INFRA^TEC.

Handling Recommendations

Please read before removing the detectors from the box.

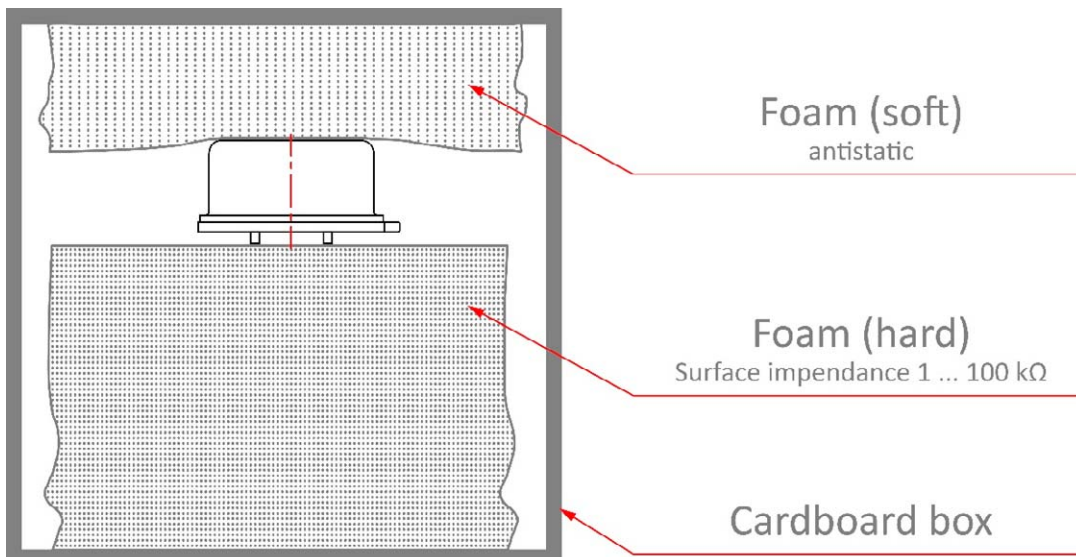
4.1 Transportation and Storage, ESD⁵ Protection



Our products comply with the normal requirements for electronic components regarding transportation and storage. Protect the components especially against exceptional mechanical loads or harmful, particularly corrosive gases or vapours. The storage temperature limits specified in the data sheets must not be exceeded.

High humidity damages electronic components. For this reason, our products should not be exposed to any extreme humidity, particularly in combination with high temperatures. Store the detectors dry and at normal room temperature. Provided that our products are delivered in moisture protected packaging, they should not get damaged.

InfraTec detectors are shipped in ESD-safe packing, which contains two types of foam:

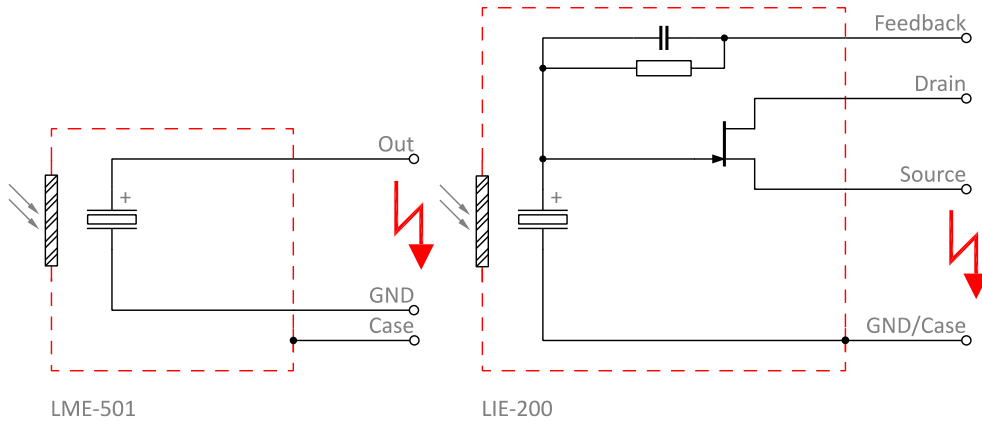


This packing is used for classic ESD protection. Otherwise, it also protects against inherent risks of pyroelectric detectors. A pyroelectric sensor element can generate a voltage of 1 kV if exposed to a temperature difference of some 10 K. In the case of an open connection configuration, which is often used for current mode detectors, high

⁵ Electrostatic discharge

Handling Recommendations

voltages might be present between the pins. Both the internally resulting charges and electrostatic discharges caused by improper handling could destroy the detector as well as the associated electronics. The conductive foam ensures gentle discharge of the charges.



Furthermore, we recommend:

- Transporting and storing the detectors in the original box until processing
- If this is not possible, short-circuit all pins for transportation and storage ($< 10 \text{ M}\Omega$)
- Process detectors in an ESD-protected production area (EPA = ESD protected area)
- Avoid rapid temperature changes $> |1 \text{ K/s}|$ of the detectors that have not yet been connected

Handling Recommendations

4.2 Processing

InfraTec detectors are generally RoHS compliant⁶ wired components that are mounted using standard soldering methods. Therefore, only limits for lead-free soldering mounting methods are given below. These also apply, of course, to methods with lead-based solders, but need not be outbid at all however, because of the generally lower process temperatures. Otherwise, the temperature profile should comply with the specifications of the solder manufacturer. In the absence of such specifications, you can use relevant standards as a guideline for the process development, e.g. DIN EN 61760-1. We normally recommend using no-clean fluxes.

4.2.1 Hand Soldering

This method is used most frequently with our detectors since it involves low investment costs and appears to be easy to implement. The risks are often underestimated here.

For a safe process configuration we recommend:

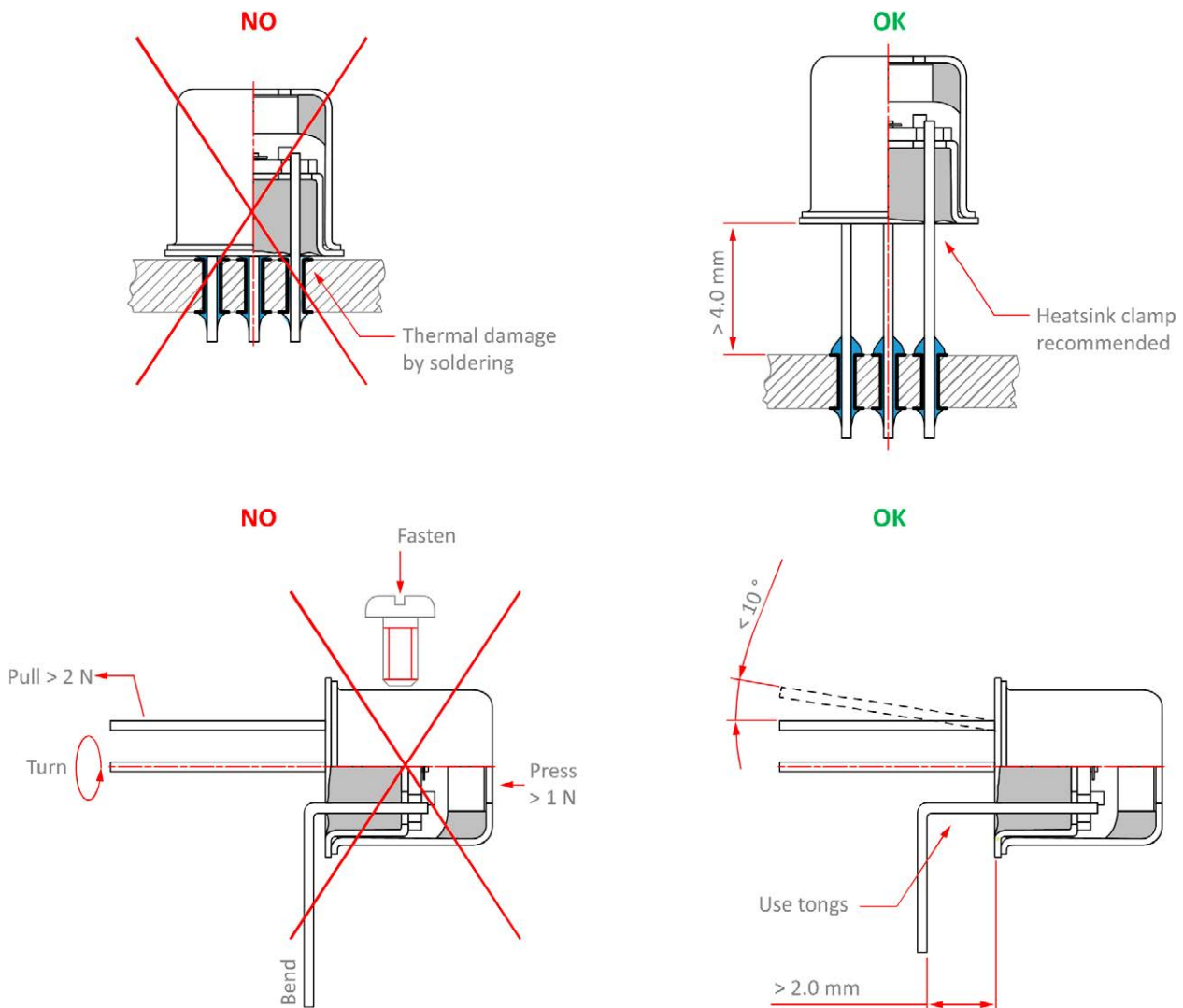
- Deploying qualified and specially trained personnel
- Using temperature-controlled soldering stations
- Using solder wire with no-clean flux
- Tension-free fixing of components before soldering
- Not touching the housing of the component with the soldering tip during soldering
- Dissipating heat on the connections using flat nose pliers before the component
- Depending on the soldering tip temperature T and the distance between the soldered joint J and housing, the following maximum soldering times in s should not be exceeded under any circumstances:

L / mm	0.5	1.5	5
T = 245 °C	4	5	10
T = 265 °C	3	4	8
T = 300 °C	2	3	5

We recommend maintaining a minimum distance of 4 mm between the bottom of the detector and the circuit board. During the soldering assembly, the greatest risks for the detector are overheating and mechanical stress. Connection pins should only be bent with great care to avoid any damage to the glass feedthroughs. Try to avoid bending at all if possible. The sensitive detector window must not be subjected to mechanical loads.

⁶ For exact term and interpretation see our FAQ on www.infratec.de

Handling Recommendations



4.2.2 Wave Soldering

Only wave soldering, particularly double waving soldering, is suitable among the machine soldering methods. While doing so, the total contact time must not exceed 10 s, and 5 s per wave, at a maximum soldering temperature of 260 °C. The advantage compared with hand soldering is the greater process reliability by defined conditions and by minimising operator influence.

4.2.3 Assembly with Conductive Adhesives

InfraTec detectors can also be assembled with conductive adhesives in a manual assembly process. Silver-based epoxy resins have been tried out. For this purpose, the contacts of the component as well as the pads of the circuit board must be designed for this assembly technology. Thus, tin-plated circuit boards are not suitable, whereas gold-plated connections are particularly suitable for conductive adhesion. The pins of our detectors are gold-plated and thus enable this specific assembly technique. The curing temperatures necessary for the adhesive present no problem for our products up to 120 °C at the usual curing times, provided that the instructions on temperature changes outlined above are followed.

Handling Recommendations

4.2.4 Cleaning

Our detectors are packed in a clean state under cleanroom conditions. Therefore, cleaning before processing is neither necessary nor recommended. Processing should be done under the cleanest conditions possible. This includes, for example, clean workplaces and room air as well as the use of suitable gloves or fingerstalls. Fingerprints consist mainly of fats and organic acids. The soldering process should be arranged in such a way that the component does not have to be cleaned afterwards. Therefore, use no-clean flux.

If, in exceptional cases, it is necessary to clean the optical windows, you should first check what kind of contamination it is. You can normally remove loosely sticking particles by blowing them off with nitrogen (max. 2 bar). Compressed air is not suitable for this, since it contains oil in most cases. Particles that stick more firmly can be removed by carefully wiping with a lint-free cotton bud. When doing so, no mechanical pressure should be exerted on the window. If this is not sufficient, the cotton bud can be moistened with a 1:1 mixture consisting of isopropyl and deionised water or with isopropyl, and then the procedure should be repeated. The cotton bud must be resistant to isopropyl. When doing this, wipe in circular movements from inside to outside. Afterwards, the cotton bud must be disposed of, especially if the adhesive edge of the cap was touched. Repeat this procedure with a dry cotton bud.

No cleaning procedure and cleaning agent may be used other than what is mentioned here.

Our experts will gladly answer your questions regarding handling.

Headquarters

InfraTec GmbH

Infrarotsensorik und Messtechnik

Gostritzer Str. 61 – 63

01217 Dresden / GERMANY

Phone +49 351 871-8625

Fax +49 351 871-8727

E-mail sensor@InfraTec.de

Internet www.InfraTec.de

USA office

InfraTec infrared LLC

Plano, TX / USA

Phone +1 877 797 6748

Fax +1 877 389 2668

E-mail sensor@InfraTec-infrared.com

Internet www.InfraTec-infrared.com

Chesterfield



Headquarters
Dresden



Shanghai

UK office

InfraTec infrared Ltd.

Chesterfield / UK

Phone +44 1246 267562

Fax +44 1246 269381

E-mail sensor@InfraTec.co.uk

Internet www.InfraTec.co.uk

China office

InfraTec Representative

Greater China

c/o German Industry & Commerce

Greater China

Shanghai / PEOPLE'S REPUBLIC OF CHINA

Phone +8621 68758536 ext 1633

E-mail sensors@InfraTec.cn

Internet www.InfraTec.cn



Latest information on the internet.

Picture credits

fotolia: © Artem Shadrin, © alexlukin, © tomertu, © Giuseppe Porzani, © S_E, © TTstudio, © Jürgen_Fälchle, © Duncan Noakes, © Dmitry Pistrov, © Paul_Fleet
iStockphoto: © christian Lagereek